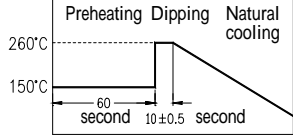
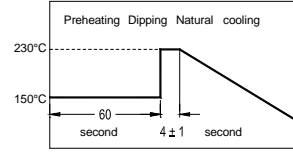
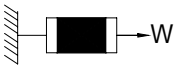
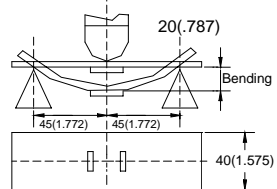
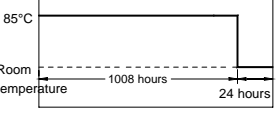


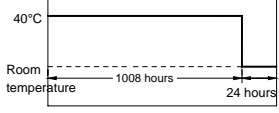
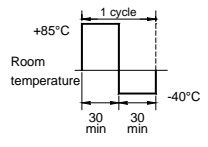
Reliability and Test Conditions (可靠性及其測試條件)

FCM/HCB/FCI Series:

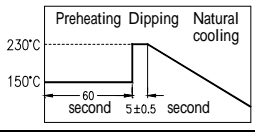
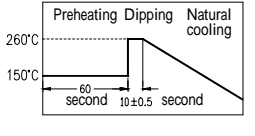
Item 項目	Performance 標準	Test Condition 測試條件
Operating temperature 操作溫度	-55 to +125 攝氏負 55 度到正 125 度	
Storage temperature and Humidity range 儲存溫度與濕度範圍	40 (max) 70%RH(max)	
Solder heat resistance 耐焊錫熱	No damage on chip More than 75% of terminal electrode should be covered with solder Impedance: within ±20% of initial value Inductance: within ±15% of initial value Q: within ±30% of initial value 產品不能破損,端電極錫覆蓋面積達 75% 以上 阻抗值:變異性在初始值 20% 以內 電感值:變異性在初始值 15% 以內 Q 值:變異性在初始值 30% 以內	Preheat: 150 ,60secs Solder : H63A Solder temperature: 260±5 Flux: rosin DIP time: 10±0.5secs 預熱: 150 ,60secs 錫爐溫度: 260±5 時間: 10±0.5secs 助焊劑: rosin 
Solderability 端面焊錫性	More than 90% of the terminal electrode should be covered with solder 端電極之錫覆蓋面積達 90% 以上	Preheat: 150 ,60secs Solder : H63A Solder temperature: 230±5 Flux: rosin DIP time: 4±1secs 預熱: 150 ,60secs 錫爐溫度: 230±5 時間: 4±0.5secs 助焊劑: rosin 
Terminal strength 端面強度	The terminal electrode and the dielectric must not be damaged by the forces applied on the right conditions. 端電極在右列測試條件下,不得與產品本體分離	Size Force Time(sec) (Kfg) 1005 0.2 1608 0.5 2012 0.6 2520 0.8 3216 1.0 >25 3225 1.0 4516 1.0 4532 1.5 5750 2.0 
Flexure strength 彎折強度	The terminal electrode and the dielectric must not be damaged by the forces applied on the right conditions. 端電極在右列測試條件下,不得與產品本體分離	Solder a chip on a test substrate, bend the substrate by 2mm (0.079in) and return 
Heat resistance 高溫放置測試	Appearance: no damage Impedance: within ±20% of initial value Inductance: within ±15% of initial value Q: within ±30% of initial value 外觀不能破損 阻抗值:變異性在初始值 20% 以內 電感值:變異性在初始值 15% 以內 Q 值:變異性在初始值 30% 以內	Applied current: max rated current Temperature : 85±5 Test time : 1008±12hrs Measure at room temperature after placing for 24hrs 須加電流:最大額定電流 溫度 : 85±5 放置時間 : 1008±12hrs 測試結束於室溫放置 24 小時,始可測試電氣特性 

Reliability and Test Conditions (可靠性及其測試條件)

FCM/HCB/FCI Series:

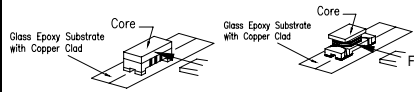
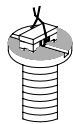
Item 項目	Performance 標準	Test Condition 測試條件
Humidity resistance 高濕放置測試	Appearance: no damage Impedance: within±20%of initial value Inductance: within±15%of initial value Q: within±30%of initial value 外觀不能破損 阻抗值:變異性在初始值 20%以內 電感值:變異性在初始值 15%以內 Q 值:變異性在初始值 30%以內	Humidity :90~95RH Temperature :40±5 Applied current: max rated current Test time : 1008±12hrs Measure at room temperature after placing for 24hrs 濕度:90~95RH, 溫度 : 40±5 須加電流:最大額定電流 放置時間 : 1008±12hrs 測試結束於室溫放置 24 小時,始可測試電氣特性 
Thermal shock (Temperature cycle) 熱衝擊試驗 (溫度週期)	Appearance: no damage Impedance: within±20%of initial value Inductance: within±15%of initial value Q: within±30%of initial value 外觀不能破損 阻抗值:變異性在初始值 20%以內 電感值:變異性在初始值 15%以內 Q 值:變異性在初始值 30%以內	Temperature :-40±5 to85±5 and keep 30 times, cycle: 5cycles Measure at room temperature after placing for 24hrs 溫度 : -40±5 to85±5 各放置 30 分鐘達 5 個週期 測試結束於室溫放置 24 小時,始可測試電氣特性 
Low temperature storage test 低溫放置測試	Appearance: no damage Impedance: within±20%of initial value Inductance: within±15%of initial value Q: within±30%of initial value 外觀不能破損 阻抗值:變異性在初始值 20%以內 電感值:變異性在初始值 15%以內 Q 值:變異性在初始值 30%以內	Temperature :-40±5 Test time : 1008±12hrs Measure at room temperature after placing for 24hrs 溫度 : -40±5 放置時間 : 1008±12hrs 測試結束於室溫放置 24 小時,始可測試電氣特性

SMH2020/2320/2520/3225/4532 Series:

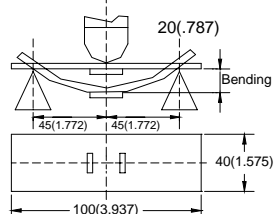
Item 項目	Performance 標準	Test Condition 測試條件
Electrical Characteristics Test		
Z(common mode) 共模阻抗	Refer to standard electrical characteristics list. 參考標準特性規格表	HP-4286A
DC Resistance 直流阻抗		HP-4338B
I.R. 絕緣阻抗		Zentech 9053A(Ultra High Resistance Meter)
Rated Current 額定電流		Applied the current to coils the impedance change should be less than ±25% to initial value and temperature rise should not be more than 30 .
Temperature Rise Test 溫昇測試		1.Applied the allowed DC current. 2.Temperature measured by digital surface thermometer
Mechanical Performance Test		
Solderability Test 焊錫性測試	More than 90% of terminal electrode should be covered with solder. 端電極之錫覆蓋面達 90%以上.	After fluxing,component shall be dipped in a melted solder bath at 230 ± 5 for 5 seconds. 
Solder Heat Resistance 耐焊錫熱	1.Components should have not evidence of electrical and mechannical damage. 2. Impedance:within ± 25% of initial value. 1.元件無明顯電性與機械性損壞. 2.共模阻抗值:變異性在初始值 25%以內.	Preheat:150 60secs. Solder:(63Sn/37Pb) Solder temperature: 260±5 Flux:rosin. Dip time:10±5 secs. 

Reliability and Test Conditions (可靠性及其測試條件)

SMH2020/2320/2520/3225/4532 Series:

Item 項目	Performance 標準	Test Condition 測試條件
Component Adhesion (Push test) 元件黏著測試 (推力測試)	Series No. F(Kg) SMH2020 0.5(min.) SMH2320 0.5(min.) SMH2520 0.8(min.) SMH3225 1.0(min.) SMH4532 1.5(min)	The device should be reflow soldered(230±5 for 10secs.)to a tinned copper substrate. A dynameters force gauge should be applied the side of the component. The device must with-ST-F Kg without allure of the termination attached to component. 
Component Adhesion (Pull test) 元件黏著測試 (拉力測試)	Series No. F(Kg) SMH2020 0.5(min.) SMH2320 0.5(min.) SMH2520 0.8(min.) SMH3225 1.0(min.) SMH4532 1.5(min)	1.Insert 10cm wire into the remaining open eye bend ,the ends of even wire lengths upward and wind together. 2.Terminal shall not be remarkably damaged. 

Mechanical Performance Test

Flexture Strength 彎折強度	The force applied should not damage the terminal electrode. 端電極在右列測試條件下,不得與產品本體分離.	Solder a chip on a test substrate, bend the substrate by 2mm(0.079in.) and return. 
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Reliability Test

High Temperature Life Test 高溫放置測試	1. Appearance:No damage. 2. Impedance:within ± 25% of initial value. No disconnection or short circuit. 1.外觀不能破損 2.阻抗值:變異性在初始值 20%以內。 內部迴路無斷線或短路.	Temperature:85±5 Time:500±12hrs Recovery: 4 to 24hrs of recovery under the standard condition after the removal from test chamber.															
Low Temperature Life Test 低溫放置測試		Temperature:-40±5 Time: 500±12hrs Recovery: 4 to 24hrs of recovery under the standard condition after the removal from test chamber.															
Thermal Shock 熱衝擊試驗		<table border="1" style="width: 100%; text-align: center;"> <thead> <tr> <th>Step</th> <th>Temperature()</th> <th>Times(min.)</th> </tr> </thead> <tbody> <tr> <td>1</td> <td>-25±3</td> <td>30±3</td> </tr> <tr> <td>2</td> <td>Room Temperature</td> <td>Within 3</td> </tr> <tr> <td>3</td> <td>85±3</td> <td>30±3</td> </tr> <tr> <td>4</td> <td>Room Temperature</td> <td>Within 3</td> </tr> </tbody> </table> Total:10 cycle Recovery: 4 to 24hrs of recovery under the standard condition after the removal from test chamber.	Step	Temperature()	Times(min.)	1	-25±3	30±3	2	Room Temperature	Within 3	3	85±3	30±3	4	Room Temperature	Within 3
Step		Temperature()	Times(min.)														
1	-25±3	30±3															
2	Room Temperature	Within 3															
3	85±3	30±3															
4	Room Temperature	Within 3															
Humidity Resistance 高濕放置測試	Temperature:40±5 Humidity:90 to 95% Applied current:Rated current Time:500±12hrs Recovery:4 to 24hrs of recovery under the standard condition after the removal from test chamber.																

B4W/B5W/T4W/T5W/SBT4F/SBT5FL/SBT5F Series:

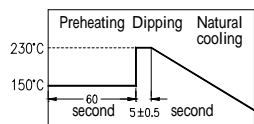
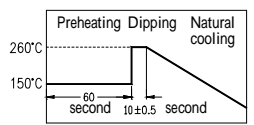
Item 項目	Performance 標準	Test Condition 測試條件
Electrical Characteristics Test		
Z(common mode) 共模阻抗值	Refer to standard electrical characteristics list.	HP-4286A
DC Resistance 直流阻抗	參考標準特性規格表	HP-4338B

Reliability and Test Conditions (可靠性及其測試條件)

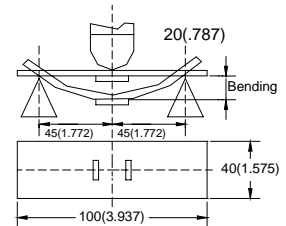
B4W/B5W/T4W/T5W/SBT4F/SBT5FL/SBT5F Series:

Item 項目	Performance 標準	Test Condition 測試條件
I.R. 絕緣阻抗		Zentech 9053A(Ultra High Resistance Meter)
Rated Current 額定電流		Applied the current to coils the impedance change should be less than $\pm 25\%$ to initial value and temperature rise should not be more than 30 .
Temperature Rise Test 溫昇測試	30 Max.(t)	1.Applied the allowed DC current. 2.Temperature measured by digital surface thermometer

Mechanical Performance Test

Solderability Test 焊錫性測試	More than 90% of terminal electrode should be covered with solder. 端電極之錫覆蓋面達 90%以上.	After fluxing,component shall be dipped in a melted solder bath at 230 ± 5 for 5 seconds.	
Solder Heat Resistance 耐焊錫熱	1.Components should have not evidence of electrical and mechanical damage. 2. Impedance:within $\pm 25\%$ of initial value. 1.元件無明顯電性與機械性損壞. 2.共模阻抗值:變異性在初始值 25%以內.	Preheat:150 60secs. Solder:(63Sn/37Pb) Solder temperature: 260 ± 5 Flux:rosin. Dip time:10±5 secs.	

Mechanical Performance Test

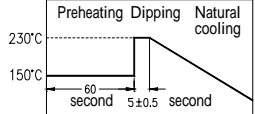
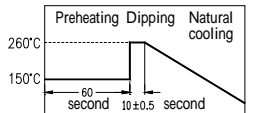
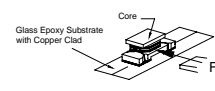
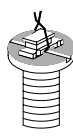
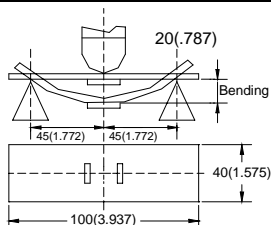
Flexure Strength 彎折強度	The force applied should not damage the terminal electrode. 端電極在右列測試條件下,不得與產品本體分離.	Solder a chip on a test substrate, bend the substrate by 2mm(0.079in.) and return.	
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Reliability Test

High Temperature Life Test 高溫放置測試	1. Appearance:No damage. 2. Impedance:within $\pm 25\%$ of initial value. No disconnection or short circuit. 1.外觀不能破損. 2.共模阻抗值:變異性在初始值 25%以內.	Temperature: 85 ± 5 Time:500±12hrs Recovery: 4 to 24hrs of recovery under the standard condition after the removal from test chamber.														
Low Temperature Life Test 低溫放置測試		Temperature: -40 ± 5 Time: 500±12hrs Recovery: 4 to 24hrs of recovery under the standard condition after the removal from test chamber.														
Thermal Shock 熱衝擊試驗		Conditions of 1 cycle <table border="1" style="width: 100%; text-align: center;"> <thead> <tr> <th>Step</th> <th>Temperature ()</th> <th>Times(min.)</th> </tr> </thead> <tbody> <tr> <td>1</td> <td>-25 ± 3</td> <td>30 ± 3</td> </tr> <tr> <td>2</td> <td>Room Temperature</td> <td>Within 3</td> </tr> <tr> <td>3</td> <td>85 ± 3</td> <td>30 ± 3</td> </tr> <tr> <td>4</td> <td>Room Temperature</td> <td>Within 3</td> </tr> </tbody> </table> <p>Total:10 cycle Recovery: 4 to 24hrs of recovery under the standard condition after the removal from test chamber.</p>	Step	Temperature ()	Times(min.)	1	-25 ± 3	30 ± 3	2	Room Temperature	Within 3	3	85 ± 3	30 ± 3	4	Room Temperature
Step	Temperature ()	Times(min.)														
1	-25 ± 3	30 ± 3														
2	Room Temperature	Within 3														
3	85 ± 3	30 ± 3														
4	Room Temperature	Within 3														
Humidity Resistance 高濕放置測試	Temperature: 40 ± 5 Humidity:90 to 95% Applied current:Rated current Time:500±12hrs Recovery:4 to 24hrs of recovery under the standard condition after the removal from test chamber.															

Reliability and Test Conditions (可靠性及其測試條件)

LPI Series:

Item 項目	Performance 標準	Test Condition 測試條件												
Electrical Characteristics Test														
Inductance 電感值	Refer to standard electrical characteristics list. 參考標準特性規格表	HP-4286A												
DC Resistance 直流阻抗		HP-4338B												
Rated Current 額定電流		Applied the current to coils the inductance change should be less than $\pm 10\%$ to initial value and temperature rise should not be more than 40 .												
Temperature Rise Test 溫昇測試	40 Max.(t)	1.Applied the allowed DC current. 2.Temperature measured by digital surface thermometer												
Mechanical Performance Test														
Solderability Test 焊錫性測試	More than 90% of terminal electrode should be covered with solder. 端電極之錫覆蓋面達 90%以上.	After fluxing,component shall be dipped in a melted solder bath at 230 ± 5 for 5 seconds. 												
Solder Heat Resistance 耐焊錫熱	1.Components should have not evidence of electrical and mechanical damage. 2. inductance:within $\pm 10\%$ of initial value. 1.元件無明顯電性與機械性損壞. 2.電感值:變異性在初始值 10%以內.	Preheat:150 60secs. Solder:(63Sn/37Pb) Solder temperature: 260 ± 5 Flux:rosin. Dip time:10±5 secs. 												
Component Adhesion (Push test) 元件黏著測試 (推力測試)	<table border="1"> <thead> <tr> <th>Size</th> <th>F(Kg)</th> </tr> </thead> <tbody> <tr> <td>4532</td> <td>1.0(Min.)</td> </tr> <tr> <td>3225</td> <td>1.0(Min.)</td> </tr> <tr> <td>3216</td> <td>0.8(Min.)</td> </tr> <tr> <td>2520</td> <td>0.5(Min.)</td> </tr> <tr> <td>2015</td> <td>0.5(Min.)</td> </tr> </tbody> </table>	Size	F(Kg)	4532	1.0(Min.)	3225	1.0(Min.)	3216	0.8(Min.)	2520	0.5(Min.)	2015	0.5(Min.)	The device should be reflow soldered(230 ± 5 for 10secs.)to a tinned copper substrate. A dynameters force gauge should be applied the side of the component. The device must with-ST-F Kg without allure of the termination attached to component. 
Size	F(Kg)													
4532	1.0(Min.)													
3225	1.0(Min.)													
3216	0.8(Min.)													
2520	0.5(Min.)													
2015	0.5(Min.)													
Component Adhesion (Pull test) 元件黏著測試 (拉力測試)	<table border="1"> <thead> <tr> <th>Size</th> <th>F(Kg)</th> </tr> </thead> <tbody> <tr> <td>4532</td> <td>1.0(Min.)</td> </tr> <tr> <td>3225</td> <td>1.0(Min.)</td> </tr> <tr> <td>3216</td> <td>0.8(Min.)</td> </tr> <tr> <td>2520</td> <td>0.5(Min.)</td> </tr> <tr> <td>2015</td> <td>0.5(Min.)</td> </tr> </tbody> </table>	Size	F(Kg)	4532	1.0(Min.)	3225	1.0(Min.)	3216	0.8(Min.)	2520	0.5(Min.)	2015	0.5(Min.)	1.Insert 10cm wire into the remaining open eye bend ,the ends of even wire lengths upward and wind together. 2.Terminal shall not be remarkably damaged. 
Size	F(Kg)													
4532	1.0(Min.)													
3225	1.0(Min.)													
3216	0.8(Min.)													
2520	0.5(Min.)													
2015	0.5(Min.)													
Mechanical Performance Test														
Flexure Strength 彎折強度	The force applied should not damage the terminal electrode. 端電極在右列測試條件下,不得與產品本體分離.	Solder a chip on a test substrate, bend the substrate by 2mm(0.079in.) and return. 												
Reliability Test														
High Temperature Life Test 高溫放置測試	1. Appearance:No damage. 2. Inductance:within $\pm 10\%$ of initial value. No disconnection or short circuit	Temperature: 85 ± 5 Time:500±12hrs Recovery: 4 to 24hrs of recovery under the standard condition after the removal from test chamber.												
Low Temperature Life Test 低溫放置測試	1.元件無明顯電性與機械性損壞. 2.共模阻抗值:變異性在初始值 25%以內.	Temperature:-40±5 Time: 500±12hrs Recovery: 4 to 24hrs of recovery under the standard condition after the removal from test chamber.												

Reliability and Test Conditions (可靠性及其測試條件)

LPI Series:

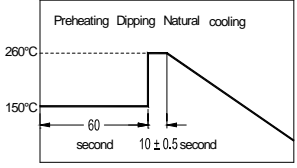
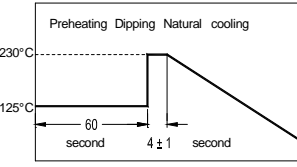
Item 項目	Performance 標準	Test Condition 測試條件															
Thermal Shock 熱衝擊試驗	1. Appearance: No damage. 2. Impedance: within $\pm 25\%$ of initial value. No disconnection or short circuit. 1. 外觀不能破損. 2. 共模阻抗值: 變異性在初始值 25% 以內.	Conditions of 1 cycle <table border="1" style="margin-left: 20px; border-collapse: collapse; width: 80%;"> <thead> <tr style="background-color: #cccccc;"> <th>Step</th> <th>Temperature()</th> <th>Times(min.)</th> </tr> </thead> <tbody> <tr> <td style="text-align: center;">1</td> <td style="text-align: center;">-25\pm3</td> <td style="text-align: center;">30\pm3</td> </tr> <tr> <td style="text-align: center;">2</td> <td style="text-align: center;">Room Temperature</td> <td style="text-align: center;">Within 3</td> </tr> <tr> <td style="text-align: center;">3</td> <td style="text-align: center;">85\pm3</td> <td style="text-align: center;">30\pm3</td> </tr> <tr> <td style="text-align: center;">4</td> <td style="text-align: center;">Room Temperature</td> <td style="text-align: center;">Within 3</td> </tr> </tbody> </table> Total: 10 cycle Recovery: 4 to 24hrs of recovery under the standard condition after the removal from test chamber.	Step	Temperature()	Times(min.)	1	-25 \pm 3	30 \pm 3	2	Room Temperature	Within 3	3	85 \pm 3	30 \pm 3	4	Room Temperature	Within 3
Step	Temperature()	Times(min.)															
1	-25 \pm 3	30 \pm 3															
2	Room Temperature	Within 3															
3	85 \pm 3	30 \pm 3															
4	Room Temperature	Within 3															
Humidity Resistance 高濕放置測試	2. 共模阻抗值: 變異性在初始值 25% 以內.	Temperature: 40 \pm 5 Humidity: 90 to 95% Applied current: Rated current Time: 500 \pm 12hrs Recovery: 4 to 24hrs of recovery under the standard condition after the removal from test chamber.															

WCI/WHI Series

Item 項目	Performance 標準	Test Condition 測試條件															
Solderability 焊錫性測試	More than 90% of the terminal electrode shall be covered with fresh solder. 端電極之錫覆蓋面達 90% 以上.	Preheat : 125 \pm 25 for 60 seconds Solder : H63A(eutectic solder) Solder temp.: 230 \pm 5 Flux : Rosin Dip time : 4 \pm 1 seconds															
Thermal Shock Test (Temp. cycle) 熱衝擊試驗 (溫度週期)	Visual examination : No mechanical damage Inductance shall not change more than $\pm 10\%$ Q: within $\pm 30\%$ of initial value 目視檢查: 無機械性損壞. 電感值: 變異性在初始值 10% 以內. Q 值: 變異性在初始值 30% 以內.	Conditions of 1 cycle <table border="1" style="margin-left: 20px; border-collapse: collapse; width: 80%;"> <thead> <tr style="background-color: #cccccc;"> <th>Step</th> <th>Temperature()</th> <th>Times(min.)</th> </tr> </thead> <tbody> <tr> <td style="text-align: center;">1</td> <td style="text-align: center;">-25\pm3</td> <td style="text-align: center;">30\pm3</td> </tr> <tr> <td style="text-align: center;">2</td> <td style="text-align: center;">Room</td> <td style="text-align: center;">Within 3</td> </tr> <tr> <td style="text-align: center;">3</td> <td style="text-align: center;">85\pm3</td> <td style="text-align: center;">30\pm3</td> </tr> <tr> <td style="text-align: center;">4</td> <td style="text-align: center;">Room</td> <td style="text-align: center;">Within 3</td> </tr> </tbody> </table> Total: 5 cycle Recovery: 4 to 24hrs of recovery under the standard condition after the removal from test chamber.	Step	Temperature()	Times(min.)	1	-25 \pm 3	30 \pm 3	2	Room	Within 3	3	85 \pm 3	30 \pm 3	4	Room	Within 3
Step	Temperature()	Times(min.)															
1	-25 \pm 3	30 \pm 3															
2	Room	Within 3															
3	85 \pm 3	30 \pm 3															
4	Room	Within 3															
Humidity Resistance Test 高濕放置測試		Temperature : 40 \pm 2 Humidity : 90~95% Applied current : per spec. Time : 500 hours															
High Resistance Test 高溫放置測試	temp.	Temperature : 85 \pm 2 Applied current : per spec. Time : 500 hours															

Reliability and Test Conditions (可靠性及其測試條件)

Surface Mount Power Inductors

Item 項目	Performance 標準	Test Condition 測試條件															
Operating Temperature 工作溫度	-20~+105																
Storage temperature 儲存溫度	-40~+85																
Rated Current 額定電流	Refer to standard electrical characteristics list. 參考標準特性規格表																
Temperature Rise Test 溫昇測試	40 max. (t) 40 度最大。																
Solder heat Resistance 耐焊錫熱	Appearance: No significant abnormality. Inductance change: Within $\pm 20\%$. 外觀無破損變形。 電感值變化在 $\pm 20\%$ 內。	Preheat:150 ,60sec. Solder : H63A Solder temperature:260 ± 5 Flux: rosin Dip time:10 ± 0.5 sec. 															
Solderability 焊錫性測試	More than 90% of the terminal electrode should be covered with solder. 端電極之錫覆蓋面達 90%以上。	Preheat:125 ± 25 ,60sec. Solder : H63A Solder temperature:230 ± 5 Flux: rosin Dip time:4 ± 1 sec. 															
Thermal shock 熱衝擊試驗	Appearance: no damage Inductance: within $\pm 20\%$ of initial value.	Condition for 1 cycle Step1:-25 ± 2 30 ± 3 min. Step2:Room temperature 15 min. Step3:+85 ± 5 30 ± 3 min. Step4:Room temperature 15 min. Number of cycles:50 <table border="1" style="margin-left: auto; margin-right: auto;"> <thead> <tr> <th>Phase</th> <th>Temperature()</th> <th>Time(min)</th> </tr> </thead> <tbody> <tr> <td>1</td> <td>-25± 2</td> <td>30± 3</td> </tr> <tr> <td>2</td> <td>Room Temp.</td> <td>15</td> </tr> <tr> <td>3</td> <td>+85± 2</td> <td>30± 3</td> </tr> <tr> <td>4</td> <td>Room Temp.</td> <td>15</td> </tr> </tbody> </table> Measured:50 times	Phase	Temperature()	Time(min)	1	-25 ± 2	30 ± 3	2	Room Temp.	15	3	+85 ± 2	30 ± 3	4	Room Temp.	15
Phase	Temperature()	Time(min)															
1	-25 ± 2	30 ± 3															
2	Room Temp.	15															
3	+85 ± 2	30 ± 3															
4	Room Temp.	15															
Humidity Resistance Test 高濕放置測試	1.外觀不能破損. 2.電感值:變異性在初始值 25%以內	Temperature:40 ± 2 . Applied current: rated current. Duration:500 hrs. Humidity:90~95%															
High Temperature Resistance Test 高溫放置測試		Temperature:85 ± 2 . Applied current: rated current. Duration:500 hrs.															